TOSHIBA

Discrete Semiconductors

Field Effect Transistor

wsilicon N Channel MOS Type (π-MOS III.5)

High Speed, High Current DC-DC Converter,

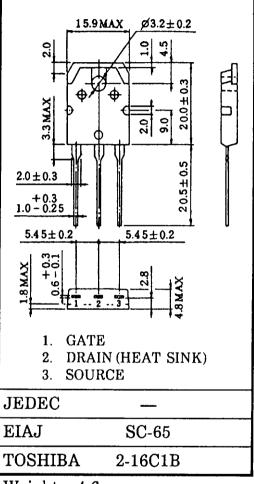
Relay Drive and Motor Drive Applications

Features

- Low Drain-Source ON Resistance
 - $R_{DS(ON)} = 0.75 \Omega$ (Typ.)
- High Forward Transfer Admittance
- |Y_{fs}| = 4.9S (Typ.)
- Low Leakage Current
- I_{DSS} = 300µA (Max.) @ V_{DS} = 500V
- Enhancement-Mode
 - $V_{th} = 2.0 \sim 4.0 V @ V_{DS} = 10 V, I_D = 1 m A$

Absolute Maximum Ratings (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V _{DSS}	500	V
Drain-Gate Voltage ($R_{GS} = 20k\Omega$)		V _{DGR}	500	V
Gate-Source Voltage		V _{GSS}	±30	V
Drain Current	DC	۱ _D	10	А
	Pulse	I _{DP}	40	
Drain Power Dissipation (Tc = 25°C)		PD	125	W
Channel Temperature		T _{ch}	150	°C
Storage Temperature Range		T _{stg}	-55 ~ 150	°C



Weight : 4.6g

Thermal Characteristics

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R _{th(ch-c)}	1.0	°C/W
Thermal Resistance, Channel to Ambient	R _{th(ch-a)}	50	°C/W

This transistor is an electrostatic sensitive device. Please handle with care.

2SK1488

Unit in mm

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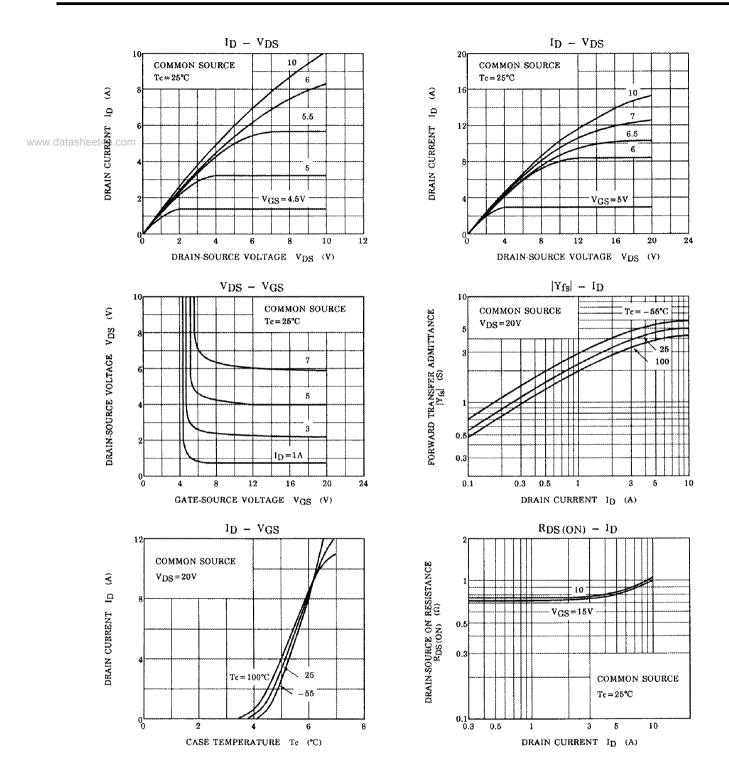
TOSHIBA CORPORATION

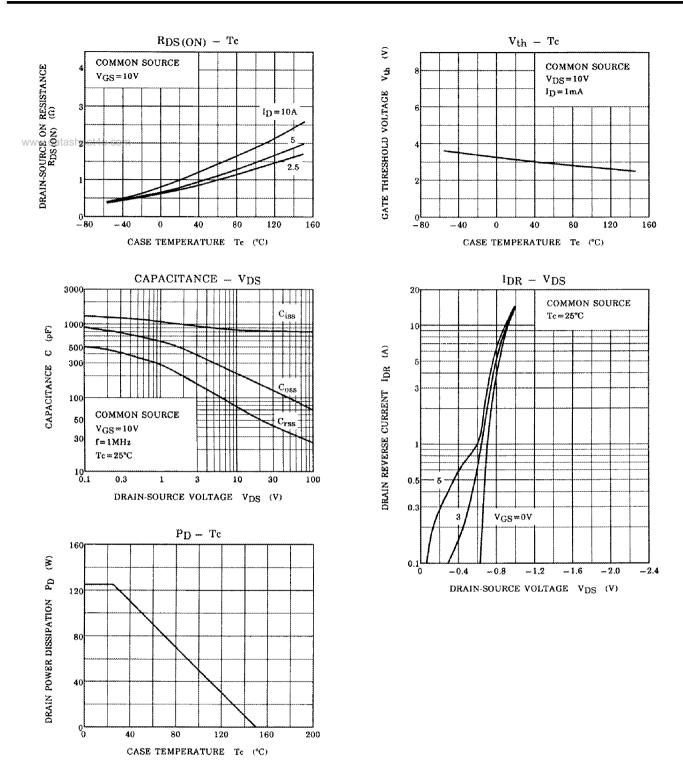
Electrical	Characteristics	(Ta = 25°C)
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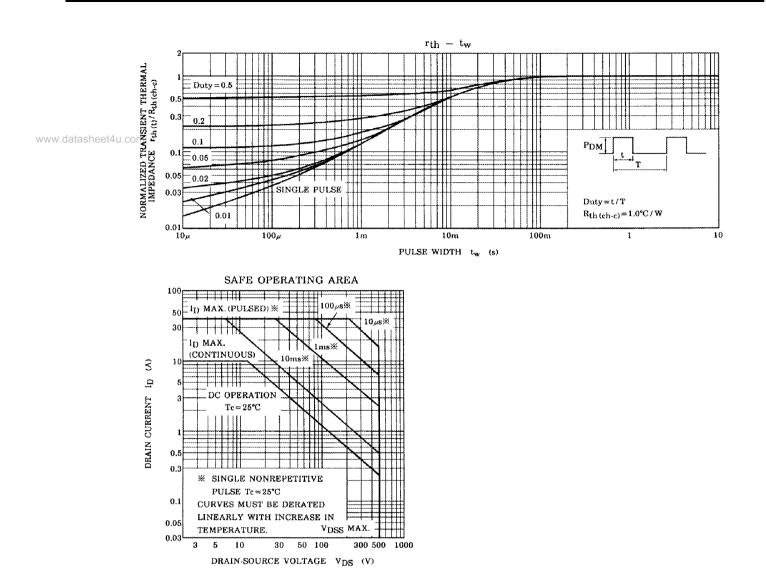
CHAR	ACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage C	Current	I _{GSS}	$V_{GS} = \pm 30 \text{V}, \ V_{DS} = 0 \text{V}$	-	_	±100	nA
Drain Cut-off C	Current	I _{DSS}	$V_{DS} = 500V, V_{GS} = 0V$	-	_	300	μA
Drain-Source B	Breakdown Voltage	V _{(BR) DSS}	$I_D = 10 \text{mA}, V_{GS} = 0 \text{V}$	500	-	-	V
Gate Threshold	Voltage	V _{th}	$V_{DS} = 10V, I_D = 1 \text{ mA}$	2.0	-	4.0	V
Drain-Source C		R _{DS (ON)}	$I_{D} = 5A, V_{GS} = 10V$	-	0.75	1.0	Ω
Forward Transf	er Admittance	Y _{fs}	$V_{DS} = 10V, I_D = 5A$	3.0	4.9	-	S
Input Capacitance Reverse Transfer Capacitance		C _{iss}	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1MHz	-	870	1100	pF
		C _{rss}		-	75	250	
Output Capacita	ance	C _{oss}		_	210	300	
	Rise Time	tr	ID=5A VOUT	-	30	90	
Switching	Turn-on Time	t _{on}		-	60	140	
Time	Fall Time	t _f		-	35	130	ns
Turn-off T	Turn-off Time	t _{off}	$V_{GS_0}^{10V}$ $C_{GS_0}^{10V}$ $R_L = 40\Omega$	-	100	300	
			$V_{IN} : t_r, t_f < 5ns, V_{DD} = 200V$ Duty $\leq 1\%, t_w = 10\mu s$				
Total Gate Charge (Gate-Source Plus Gate-Drain)		Qg	$V_{DD} = 400V, V_{GS} = 10V,$ $I_{D} = 10A$	-	40	85	nC
Gate-Source Charge		Q _{gs}		-	16	-	
Gate-Drain ("M	liller") Charge	Q _{gd}	1	-	24	-	

Source-Drain Diode Ratings and Characteristics (Ta = 25° C)

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I _{DR}	_	-	-	10	A
Pulse Drain Reverse Current	I _{DRP}	_	-	-	40	A
Diode Forward Voltage	V _{DSF}	I _{DR} = 10A, V _{GS} = 0V	-	-	-2.0	V
Reverse Recovery Time	t _{rr}	$I_{DR} = 10A, V_{GS} = 0V$	-	360	-	ns
Reverse Recovered Charge	Q _{rr}	dI _{DR} /dt = 100A/µs	-	3.0	-	μC







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